**Part Number :** 2044731114
**Product Description :** DDR5 RDIMM Socket, Vertical Surface Mount, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm to 3.18mm, Black Housing, Black Latch, with Pick and Place Tape
**Series Number :** 204473
**Status :** Active
**Product Category :** Memory Module Connectors



## Documents & Resources

### Drawings

2044731114_sd.pdf

2044730003-000.pdf

2044730000-000.pdf

2044730000-000.zip

### Specifications

2044730000-AS-000.pdf

2044730002-000.pdf

2044730001-PS-000.pdf

## Product Environment Compliance

### Compliance

| | |
|---|---|
| GADSL/IMDS | Not Relevant |
| China RoHS | per SJ/T 11365-2006 |
| EU ELV | Not Relevant |
| Low-Halogen Status | Low-Halogen per IEC 61249-2-21 |
| REACH SVHC | Not Contained per D(2025)4165-DC (25 June 2025) |
| EU RoHS | Compliant per EU 2015/863 |

Compliance Statements

- EU RoHS

- REACH SVHC
- Low-Halogen

Industry Documents
- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest
- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

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## Part Details

### General

| | |
|---|---|
| Status | Active |
| Category | Memory Module Connectors |
| Series | 204473 |
| Description | DDR5 RDIMM Socket, Vertical Surface Mount, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm to 3.18mm, Black Housing, Black Latch, with Pick and Place Tape |
| Component Type | Socket |
| JEDEC Outline | MO-329 |
| Product Name | DDR5 DIMM |
| UPC | 191128978811 |

### Agency

| | |
|---|---|
| CSA | 1409726 |
| UL | E29179 |

### Electrical

| | |
|---|---|
| Current - Maximum per Contact | 1.0A |
| Voltage - Maximum | 29V AC (RMS)/DC |

### Physical

| | |
|---|---|
| Circuits (Loaded) | 288 |
| Circuits (maximum) | 288 |
| Durability (mating cycles max) | 25 |
| Entry Angle | Vertical (Top Entry) |
| Flammability | 94V-0 |
| Housing Color | Black |
| Keying to Mating Part | Yes |
| Latch Color | Black |
| Material - Metal | Copper Alloy |
| Material - Plating Mating | Gold |
| Material - Plating Termination | Tin |
| Material - Resin | High Temperature Polyamide |
| Net Weight | 6.287/g |
| Packaging Type | Tray |
| PCB Locator | Yes |
| PCB Retention | Yes |
| PCB Thickness - Recommended | 1.57mm, 3.18mm |
| Pitch - Mating Interface | 0.85mm |
| Pitch - Termination Interface | 0.85mm |
| Plating min - Mating | 0.762µm |
| Plating min - Termination | 2.540µm |
| Temperature Range - Operating | -55° to +85°C |
| Termination Interface Style | Surface Mount |

**Solder Process Data**

| | |
|---|---|
| Max-Duration | 10 |
| Lead-Free Process Capability | REFLOW |
| Max-Cycle | 3 |
| Max-Temp | 260 |

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## Mates With / Use With

**Mates with Part(s)**

| Description | Part Number |
|---|---|
| Mates With | Memory Module Cards of 1.27mm |

| | Thickness |
|---|---|